In the Claims:

1. (currently amended) A method of resin-encapsulating an electronic component mounted on a main surface of a board, using a mold pair having an upper mold and a lower mold, comprising the steps of:

attaching said board on said upper mold;

generating melted resin in a cavity provided in said lower ~~mold~~; mold by melting a solid resin material in said cavity;

immersing said electronic component in said melted resin in said cavity by closing said mold pair; and

forming a resin [[~~mold~~]] molded product including said electronic component in a set resin by setting said melted resin to produce said set resin in said cavity.

2. (currently amended) The method of resin encapsulation according to claim 1, ~~wherein in~~ further comprising, before said step of generating melted resin, ~~said melted resin is generated by heating a~~ another step of placing said solid resin material ~~placed~~ in said cavity.

3. (original) The method of resin encapsulation according to claim 1, wherein

an electrode of said board and an electrode of said electronic component are connected by a conductive material forming a loop in a prescribed plane; and

in said step of immersing said electronic component in said melted resin, said prescribed plane moves substantially vertically to a main surface of said melted resin.

4. (original) A method of manufacturing a semiconductor device, using the method of resin encapsulation according to claim 1.

5. (original) A method of resin-encapsulating an electronic component mounted on a main surface of a board, using a mold pair having an upper mold and a lower mold and a solid resin material for resin encapsulation, comprising the steps of:

placing said board on said lower mold;

placing said resin material on a main surface of said board such that said resin material is not in contact with a conductive material connecting an electrode of said board with an electrode of said electronic component;

closing said mold pair;

generating melted resin on the main surface of said board and enclosing said electronic component in said melted resin by heating said resin material; and

forming a resin mold product by setting said melted resin.

6. (original) The method of resin encapsulation according to claim 5, wherein

said resin material has such size and shape that correspond to size and shape of said cavity; and

said melted resin is generated by heat transmitted from said upper mold to said resin material.

7. (original) The method of resin encapsulation according to claim 5, wherein

said resin material is formed such that a space formed by said board and said resin material encloses said electronic component, when said resin material is placed on the main surface of said board; and

said space is set to have such a size that said resin material is not in contact with the conductive material connecting the electrode of said board with the electrode of said electronic component.

8. (original) A method of manufacturing a semiconductor device, using the method of resin encapsulation according to claim 5.

9. (currently amended) A solid resin material consisting of a solid resin material adapted, sized and shaped to be placed in a mold cavity provided in a mold pair, and adapted to be used as a raw material [[of]] for being melted in said

cavity to produce thereof a melted resin in a method of resin-encapsulating an electronic component mounted on a main surface of a board in said cavity by encapsulating said electronic component in said melted resin and setting said melted resin in said cavity, wherein said solid resin material has ~~generated in a cavity provided in a mold pair, having~~ such a size and a shape that correspond to a size and a shape of said cavity.

10. (currently amended) The resin material according to claim 9, ~~formed~~ adapted, sized and shaped such that a space formed by said board and said resin material encloses said electronic component, when said resin material is placed on the main surface of said board; wherein said space is set to have such a size that said resin material is not in contact with [[~~the~~]] a conductive material connecting [[~~the~~]] an electrode of said board with [[~~the~~]] an electrode of said electronic component.

11. (original) The resin material according to claim 9, wherein a notch is formed in said resin material.

12. (new) The resin material according to claim 9, being a solid plate consisting of said solid resin material and having a stepped sectional shape with stepped side walls.

13. (new) The method of resin encapsulation according to claim 1, wherein said step of placing said solid resin material in said cavity comprises transporting and depositing said solid resin material into said cavity using a vacuum-holding conveyor.

[RESPONSE CONTINUES ON NEXT PAGE]